



Material Content Data Sheet



Sales Product Name		BSC084P03NS3E G		Issued		29. August 2013		
MA#		MA000509226						
Package		PG-TDSON-8-5		Weight*		119.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.54	1.54	15368	15368
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.62	31.66	316270	316682
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	478	478
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		713	
	plastics	epoxy resin	-	6.046	5.06		50642	
	inorganic material	silicondioxide	60676-86-0	36.449	30.53	35.66	305279	356634
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12158	12158
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.037	0.03		308	
	noble metal	silver	7440-22-4	0.046	0.04		385	
	non noble metal	lead	7439-92-1	1.758	1.47	1.54	14721	15414
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.48	9.49	94811	94934
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
	non noble metal	copper	7440-50-8	22.292	18.67	18.70	186703	186946
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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